Invited Paper for Garrou/Franzon 3D session

Speaker: Paul Enquist

Low Temperature Direct Bond Technology for 3D Microelectronics Integration and Wafer Scale Packaging

3D microelectronics integration and wafer scale packaging promise improvements in functional density and cost compared to conventional 2D microelectronics and packaging technologies. The ZiBond™ and DBI® low temperature direct bond technologies developed by Ziptronix have a number of inherent performance and cost advantages compared to other 3D technologies. This paper will describe the ZiBond™ and DBI® technologies and applications that will drive their volume manufacturing adoption.